

IGBT

SGW13N60UFD

Ultra-Fast IGBT

General Description

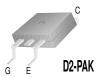
Fairchild's UFD series of Insulated Gate Bipolar Transistors (IGBTs) provides low conduction and switching losses. The UFD series is designed for applications such as motor control and general inverters where high speed switching is a required feature.

Features

- · High speed switching
- Low saturation voltage : $V_{CE(sat)} = 2.1 \text{ V } @ I_C = 6.5 \text{A}$
- · High input impedance
- CO-PAK, IGBT with FRD : t_{rr} = 37ns (typ.)

Applications

AC & DC motor controls, general purpose inverters, robotics, and servo controls.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Description		SGW13N60UFD	Units
V _{CES}	Collector-Emitter Voltage		600	V
V _{GES}	Gate-Emitter Voltage		± 20	V
	Collector Current	@ $T_C = 25^{\circ}C$	13	А
IC	Collector Current	@ T _C = 100°C	6.5	А
I _{CM (1)}	Pulsed Collector Current		52	Α
I _F	Diode Continuous Forward Current	@ T _C = 100°C	8	Α
I _{FM}	Diode Maximum Forward Current		56	Α
P _D	Maximum Power Dissipation	@ $T_C = 25^{\circ}C$	60	W
	Maximum Power Dissipation	@ T _C = 100°C	25	W
T _J	Operating Junction Temperature		-55 to +150	°C
T _{stg}	Storage Temperature Range		-55 to +150	°C
T _L	Maximum Lead Temp. for Soldering Purposes from Case for 5 Seconds		300	°C

Notes:(1) Repetitive rating: Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction-to-Case		2.0	°C/W
$R_{\theta JC}(DIODE)$	Thermal Resistance, Junction-to-Case		3.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (PCB Mount) (2)		40	°C/W

(2) Mounted on 1" squre PCB (FR4 or G-10 Material)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chai	racteristics					
BV _{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	600			V
ΔB _{VCES} / ΔT _J	Temperature Coefficient of Breakdown Voltage	V _{GE} = 0V, I _C = 1mA		0.6		V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			250	uA
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Chai	racteristics					
V _{GE(th)}	G-E Threshold Voltage	$I_C = 6.5 \text{mA}, V_{CE} = V_{GE}$	3.5	4.5	6.5	V
	Collector to Emitter	$I_{C} = 6.5A$, $V_{GE} = 15V$		2.1	2.6	V
V _{CE(sat)}	Saturation Voltage	$I_C = 13A$, $V_{GE} = 15V$		2.6		V
D	- Ohawastawiatiaa				•	
C _{ies}	c Characteristics Input Capacitance			375		pF
C _{oes}	Output Capacitance	$V_{CE} = 30V_{,} V_{GE} = 0V_{,}$		63		pF
C _{res}	Reverse Transfer Capacitance	f = 1MHz		13		pΓ
t _{d(on)}	ng Characteristics Turn-On Delay Time			20		ns
t _r	Rise Time			27		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 6.5 \text{A},$		70	130	ns
t _f	Fall Time	$R_G = 50\Omega$, $V_{GE} = 15V$,		97	150	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C		85		uJ
E _{off}	Turn-Off Switching Loss	1		95		uJ
E _{ts}	Total Switching Loss			180	270	uJ
t _{d(on)}	Turn-On Delay Time			30		ns
t _r	Rise Time	1		32		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 6.5 \text{A},$		85	200	ns
t _f	Fall Time	$R_G = 50\Omega$, $V_{GE} = 15V$,		168	250	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 125°C		180		uJ
E _{off}	Turn-Off Switching Loss			165		uJ
E _{ts}	Total Switching Loss	<u> </u>		345	500	uJ
Q_g	Total Gate Charge	V - 200 V I 6 5 4		25	35	nC
Q _{ge}	Gate-Emitter Charge	$V_{CE} = 300 \text{ V}, I_{C} = 6.5 \text{A},$ $V_{GE} = 15 \text{V}$		7	12	nC
Q _{gc}	Gate-Collector Charge	VGE - 13V		8	14	nC
L _e	Internal Emitter Inductance	Measured 5mm from PKG		7.5		nН

Electrical Characteristics of DIODE T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
V _{FM}	Diode Forward Voltage	I _F = 8A	$T_C = 25^{\circ}C$		1.4	1.7	V
V ⊢M	blode Forward voltage	IF = OA	$T_C = 100^{\circ}C$		1.3		1 V
+	t _{rr} Diode Reverse Recovery Time		$T_C = 25^{\circ}C$		37	55	ne
۲rr			T _C = 100°C		55		ns
1	Diode Peak Reverse Recovery Current	I _F = 8A,	$T_C = 25^{\circ}C$		3.5	5.0	۸
^I rr		di/dt = 200A/us	T _C = 100°C		4.5		Α
	Diode Reverse Recovery Charge		$T_C = 25^{\circ}C$		65	138	~C
Q_{rr}			T _C = 100°C		124		nC

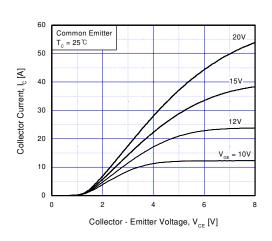


Fig 1. Typical Output Characteristics

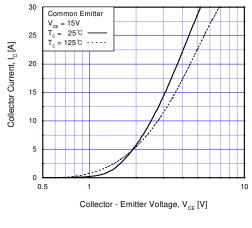


Fig 2. Typical Saturation Voltage Characteristics

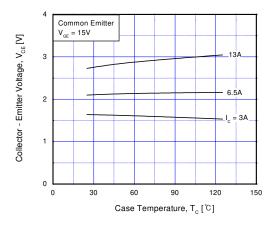


Fig 3. Saturation Voltage vs. Case
Temperature at Variant Current Level

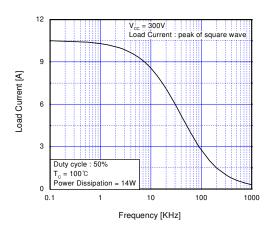


Fig 4. Load Current vs. Frequency

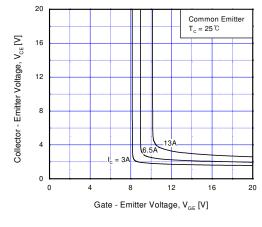


Fig 5. Saturation Voltage vs. V_{GE}

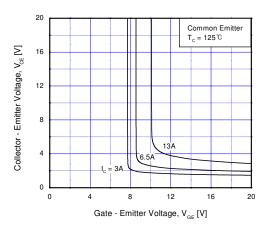
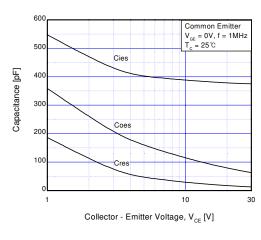


Fig 6. Saturation Voltage vs. V_{GE}

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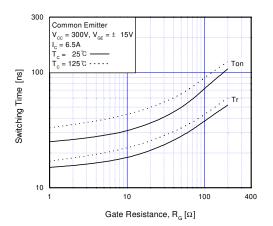
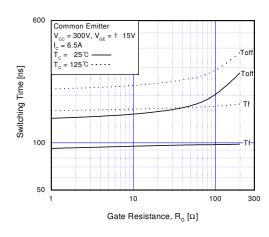


Fig 7. Capacitance Characteristics

Fig 8. Turn-On Characteristics vs.
Gate Resistance



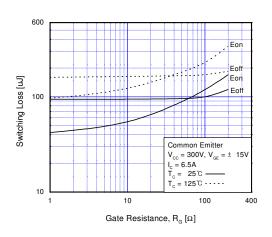
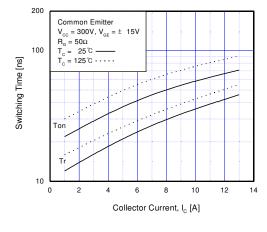


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

Fig 10. Switching Loss vs. Gate Resistance



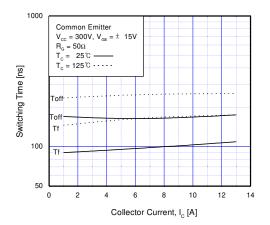
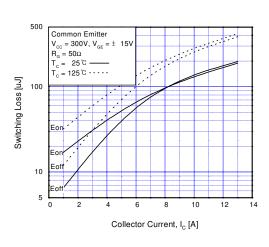


Fig 11. Turn-On Characteristics vs. Collector Current

Fig 12. Turn-Off Characteristics vs. Collector Current



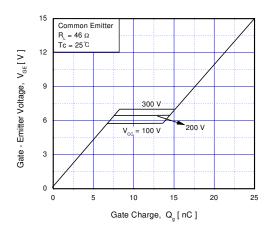
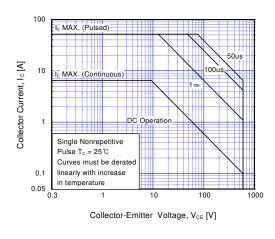


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



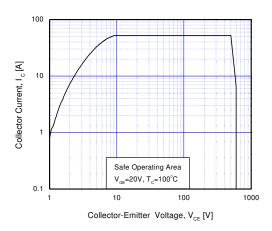


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA Characteristics

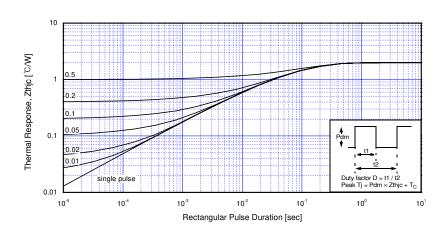
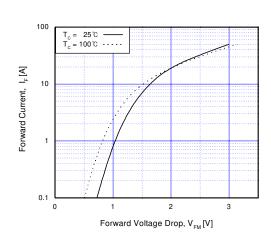


Fig 17. Transient Thermal Impedance of IGBT



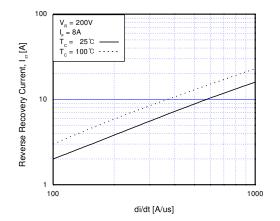
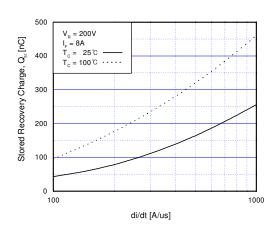


Fig 18. Forward Characteristics

Fig 19. Reverse Recovery Current



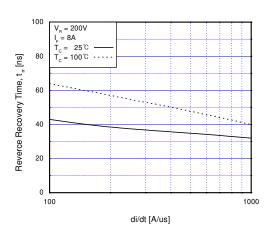
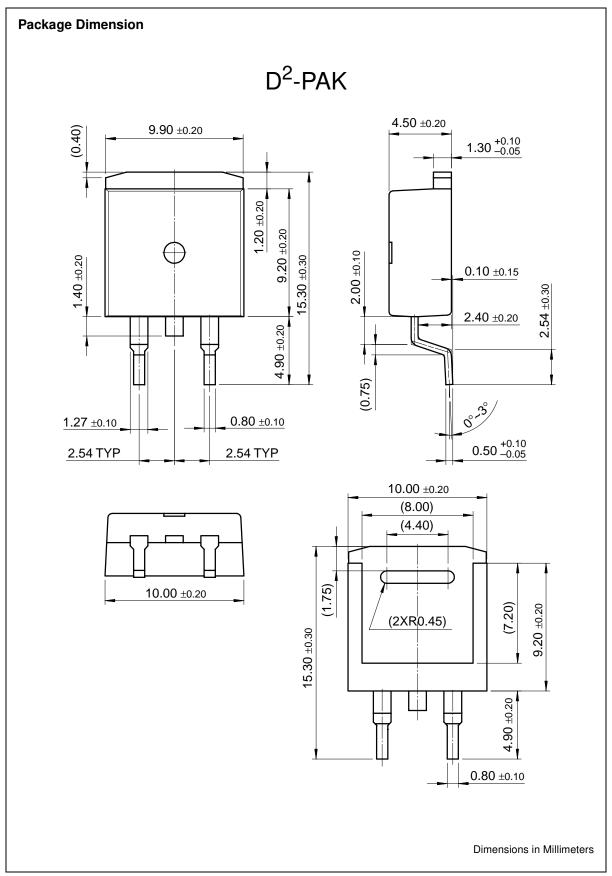


Fig 20. Stored Charge

Fig 21. Reverse Recovery Time



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^{* 1,000} piece Budgetary Pricing

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